Outline

RX23W Group BLE Module Firmware Integration Technology (FIT) has been updated from Rev.2.31 to Rev.2.40.

Since the R_BLE_Open API has been modified, please upgrade the revision if you are using this FIT module.

1. Products to Be Updated

RX23W Group BLE Module Firmware Integration Technology
Rev.1.00, 1.01, 1.10, 2.00, 2.10, 2.11, 2.20, 2.30, 2.31

2. Description

The main change is as follows. Refer to the Application Note’s Revision History for other changes.

RX23W Group BLE Module Firmware Integration Technology Application Note

2.1 Issue Fixed

2.1.1 Adjustment of Initialization Stability Wait Time of R_BLE_Open

There was an issue that H/W initialization error occurred in the initialization process of the R_BLE_Open API depending on the conditions when power was applied, and the r_ble_rf_control_error function was called with err_no "0xFF04". As a modification of this issue, the stable waiting time of the initialization process in R_BLE_Open has been adjusted. This modification will increase the processing time of R_BLE_Open by about 200msec.

2.1.2 Stabilization of peripheral communication operation when Connection Latency is enabled

Fixed an issue when the RX23W is a peripheral role and the connection latency is non-zero, data transmission timing on the RX23W side rarely goes out of sync with the central device, causing a delay in data transmission until the RX23W resynchronization.

2.1.3 Fixed an issue the bonding information in the data flash cannot be deleted

Fixed an issue that the remaining bonding information cannot be deleted due to incorrect references to the bonding information in the data flash after using the R_BLE_SECD_DelRemKeys API with specified BD address to delete a bonding information set when two or more bonding information sets are registered.
3. Updating the Product

Download the FIT module using the RX Smart Configurator and update the software component version. For details, visit the following web site and refer to the RX Smart Configurator User's Guide.

Firmware Integration Technology (FIT) | Renesas
Revision History

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<th>Rev.</th>
<th>Date</th>
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<tr>
<td>1.00</td>
<td>Jul.01.22</td>
<td>First edition issued</td>
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Corporate Headquarters
TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Contact information
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